


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/24/14536	
1.3 Title of PCN	JSCC(China) UFQFPN 5X5 32L, UFQFPN 7X7 48L and VFQFPN 8X8 68L new BOM for STM32H50x & STM32H56x/H57x listed product .	
1.4 Product Category	STM32H503xx, STM32H562xx, STM32H563xx & STM32H573xx	
1.5 Issue date	2024-04-04	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter	StatsChipPAC JSCC Jiangyin China

4. Description of change

	Old	New
4.1 Description	Assembly lines / wire bonding: - JSCC (China) / Gold wire Packages: - UFQFPN 5X5 32L - UFQFPN 7X7 48L - VFQFPN 8X8 68L	Assembly lines / wire bonding: - JSCC (China) / Copper Palladium wire additional source - JSCC (China) / Gold wire Packages: - UFQFPN 5X5 32L - UFQFPN 7X7 48L - VFQFPN 8X8 68L
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No change in Form, no change in Fit, no change in Function. Package darkness might change depending on molding compound. Pin1 identifier remain in the same corner but might slightly change in terms of form and positioning.	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional back-end assembly line to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Traceability ensure by ST internal tools
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7. Timing / schedule

7.1 Date of qualification results	2024-06-25
7.2 Intended start of delivery	2024-06-25
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	14536 MDRF-GPM-RER2220 JSCC UQFN VQFN CuPdAu Reliability PLAN.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2024-04-04

9. Attachments (additional documentations)

14536 Public product.pdf
14536 MDRF-GPM-RER2220 JSCC UQFN VQFN CuPdAu Reliability PLAN.pdf
14536 PCN14536_Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H503KBU6	

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